

VieTape TIM9001

HIGH THERMALLY CONDUCTIVE GAP FILLER PAD

DESCRIPTION

VieTape TIM9001 is high conductive pad designed with low thermal resistance and excellent electrical insulation. It provides good performance at low compression and highly stable at a wide range of temperature (-40°C-150°C).

APPLICATION

Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, ...

TYPICAL PERFORMANCE PROPERTIES

PROPERTIES	VALUE	METHOD
Appearance	Green	-
Thickness	0.5-6.0 mm	ASTM D374
Density	3.1- 3.3 g/cm ³	ASTM D792
Weight loss	≤ 1.0%	ASTM E595
Hardness	40 shore 00	ASTM D2240
Breakdown Voltage	>5.0 kV/mm	ASTM D149
Volume Resistivity	10 ¹⁰ Ohm-cm	ASTM D257
Dielectric Constant@1MHz	7.0	ASTM D150
Thermal conductivity	5.0 W/m.K	ISO22007-2
Thermal resistance	0.31 °C.in ² /W	ASTM D5470
Working Temperature	-40 - 150°C	-

SHELF LIFE AND STORAGE

12 months from date of manufacture when stored at 10-30°C and 40 - 50% relative humidity. Avoid high humidity and exposure to sunlight.

CAUTION

For safe handling information on this product, please review the Safety Data Sheet, SDS

The data contained in this bulletin is provided only as a guide for evaluation/consideration. These material characteristics are typical properties that are based on a limited number of samples tested in the laboratory. We cannot assume responsibility for results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any product or method. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide.

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